

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) A capsule [[type]] curing agent which comprises a core comprising an amine [[type]] curing agent (A) having at least one tertiary amino group in one molecule thereof and a capsule ~~and a membrane covering~~ said core, wherein said capsule membrane [[has]] comprises a shell of a reaction product between the amine curing agent (A) and an epoxy resin (D) in which a total amount of chlorines in the epoxy resin is not more than 400 ppm and an intermediate layer having a bonding group (x) absorbing infrared [[ray]] rays of a wave-number of 1630 to 1680 cm^{-1} and/or a bonding group (y) absorbing infrared [[ray]] rays of a wave-number of 1680 to 1725 cm^{-1} , ~~and contains cured material of an epoxy resin by~~ the amine type curing agent (A) as a curing agent, and a weight ratio of the core [[and]] to the capsule membrane is 100:1 to 100:100.
2. (Currently amended) The capsule [[type]] curing agent according to ~~Claim~~ claim 1, wherein in ^{13}C -NMR spectrum of the capsule membrane, a ratio of a largest peak height between 37 ppm to 47 ppm to a largest peak height between 47 ppm to 57 ppm is not lower than 3 and not higher than 7.
3. (Currently amended) The capsule [[type]] curing agent according to ~~Claim~~ claim 1 [[or 2]], wherein a melt viscosity of the amine [[type]] curing agent (A) at 160°C is not higher than 10 $\text{Pa}\cdot\text{s}$.
4. (Cancelled).

5. (Currently amended) The capsule [[type]] curing agent according to any one of Claims claim 1 [[to 4]], wherein a total amount of chlorines in the amine [[type]] curing agent (A) is not more than 400 ppm.

6. (Currently amended) The capsule [[type]] curing agent according to any one of Claims claim 1 [[to 5]], wherein the amine [[type]] curing agent (A) is a reaction product between an epoxy resin (B) having a total amount of chlorines of not more than 400 ppm and an amine compound (C).

7-8. (Cancelled).

9. (Currently amended) A masterbatch [[type]] curing agent comprising 100 parts by weight of the capsule [[type]] curing agent according to any one of Claims claim 1 [[to 8]] and 10 to 50,000 parts by weight of an epoxy resin (E).

10. (Currently amended) An epoxy resin composition comprising, as main components, 100 parts by weight of an epoxy resin (F) and the capsule type curing agent according to any one of Claims 1 to 8 or 0.1 to 100 parts by weight of the masterbatch [[type]] curing agent according to Claim claim 9 or a mixture thereof in such an amount as the total amount of the capsule type curing agents is 0.1 to 100 parts by weight.

11. (Currently amended) An epoxy resin composition comprising, as main components, 100 parts by weight of [[the]] an epoxy resin (F), 1 to 200 parts by weight of at least one kind of a curing agent (G) selected from the group consisting of acid anhydrides, phenols, hydrazides and quanidines, and the capsule type curing agent according to any one of Claims 1 to 8 or 0.1 to 100 parts by weight of the masterbatch [[type]] curing agent according to Claim claim 9 or a mixture thereof in

~~such an amount as the total amount of the capsule type curing agent is 0.1 to 100 parts by weight.~~

12. (Currently amended) An anisotropic conductive material containing comprising the epoxy resin composition masterbatch curing agent according to ~~Claim 10 or 11~~ claim 9.

13. (Currently amended) A conductive adhesive material containing the ~~epoxy resin composition masterbatch curing agent~~ according to ~~Claim 10 or 11~~ claim 9.

14. (Currently amended) An insulating adhesive material containing the ~~epoxy resin composition masterbatch curing agent~~ according to ~~Claim 10 or 11~~ claim 9.

15. (Currently amended) An encapsulant containing the ~~epoxy resin composition masterbatch curing agent~~ according to ~~Claim 10 or 11~~ claim 9.

16. (New) An anisotropic conductive material comprising the epoxy resin composition according to claim 10.

17. (New) A conductive adhesive material containing the epoxy resin composition according to claim 10.

18. (New) An insulating adhesive material containing the epoxy resin composition according to claim 10.

19. (New) An encapsulant containing the epoxy resin composition according to claim 10.

20. (New) An anisotropic conductive material comprising the epoxy resin composition according to claim 11.

21. (New) A conductive adhesive material containing the epoxy resin composition according to claim 11.

22. (New) An insulating adhesive material containing the epoxy resin composition according to claim 11.

23. (New) An encapsulant containing the epoxy resin composition according to claim 11.